

PART INFORMATION

Mfg Item Number	MPXV5010GC7U
Mfg Item Name	SMOUTLN DIP W/AXIAL PORT

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2013-01-08
Response Document ID	0883K50010S519A1.24
Contact Name	Freescale Semiconductor Inc
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Representative Title	EPP Customer Response
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URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	Yes
Pb Free	Yes
HalogenFree	No
Plating Indicator	e4
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MPXV5010GC7U
Mfg Item Name	SMOUTLN DIP W/AXIAL PORT
Version	ALL
Weight	1.303800
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	
Max Time at Peak Temperature	
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Cap/Cover	0.1958						g				
Cap/Cover		Metals	Chromium, metal	7440-47-3		0.03286	g	180216	18.0216	27063	2.7063
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9		0.000059	g	300	0.03	45	0.0045
Cap/Cover		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.000078	g	400	0.04	59	0.0059
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3		0.00147	g	7509	0.7509	1127	0.1127
Cap/Cover		Metals	Iron, metal	7439-89-6		0.156947	g	801563	80.1563	120378	12.0378
Cap/Cover		Metals	Manganese, metal	7439-96-5		0.00196	g	10012	1.0012	1503	0.1503
Non-Conductive Epoxy/Adhesive	0.0028						g				
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-94-1		0.000029	g	10324	1.0324	22	0.0022
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1		0.000344	g	122911	12.2911	263	0.0263
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.001101	g	393313	39.3313	544	0.0544
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.000819	g	221239	22.1239	474	0.0474
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-61-9		0.000413	g	147493	14.7493	316	0.0316
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.000262	g	93412	9.3412	200	0.02
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.000032	g	11308	1.1308	24	0.0024
Port	0.2535						g				
Port		Metals	Antimony, metal	7440-36-0		0.002535	g	10000	1	1944	0.1944
Port		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.002535	g	10000	1	1944	0.1944
Port		Plastics/polymers	Polybutylene terephthalate (PBT)	30985-26-6		0.111539	g	440000	44	8550	8.555
Port		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.084923	g	335000	33.5	65135	6.5135
Port		Glass	Fibrous-glass-wool	65997-17-3		0.051968	g	205000	20.5	39858	3.9858
Bonding Wire	0.001						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.001	g	1000000	100	786	0.0786
Gel Die Encapsulant	0.028						g				
Gel Die Encapsulant		Solvents, additives, and other materials	Proprietary Material-Other inorganic fluorine compounds and their aqueous salts	-		0.028	g	1000000	100	21475	2.1475
Copper Lead Frame	0.7829						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.182267	g	229874	22.9874	139798	13.9798
Copper Lead Frame		Metals	Gold, metal	7440-57-5		0.000171	g	216	0.0216	131	0.0131
Copper Lead Frame		Solvents, additives, and other materials	Proprietary Material-inorganic compounds.	-		0.117834	g	148612	14.8612	90378	9.0378
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.000156	g	197	0.0197	119	0.0119
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.004443	g	5603	0.5603	3407	0.3407
Copper Lead Frame		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.000033	g	41	0.0041	25	0.0025
Copper Lead Frame		Metals	Nickel, metal	7440-02-0		0.006577	g	8295	0.8295	5044	0.5044
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.000335	g	422	0.0422	256	0.0256
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.361065	g	455373	45.5373	276945	27.6945
Copper Lead Frame		Glass	Fibrous-glass-wool	65997-17-3		0.119726	g	150997	15.0997	91829	9.1829
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.000057	g	72	0.0072	43	0.0043
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.000236	g	298	0.0298	181	0.0181
Bonding Agent	0.0212						g				
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-		0.00954	g	450000	45	7317	0.7317
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-		0.00053	g	25000	2.5	406	0.0406
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00053	g	25000	2.5	406	0.0406
Bonding Agent		Plastics/polymers	Other phenolic resins	-		0.0106	g	500000	50	8130	0.813
Silicon Semiconductor Die	0.0086						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000172	g	20000	2	131	0.0131
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.008428	g	980000	98	6464	0.6464

LINKS

MCD LINK

Freescale website <http://www.freescale.com>

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf

Conflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf

FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request [https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod](https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware+Product+Support&defaultTopic=Environmentally+Preferred+Prod)

LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v0.9 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPXV5010GC7U_IPC1752_v09.xml

http://www.freescale.com/mcds/MPXV5010GC7U_IPC1752_v11.xml

http://www.freescale.com/mcds/MPXV5010GC7U_IPC1752A.xml